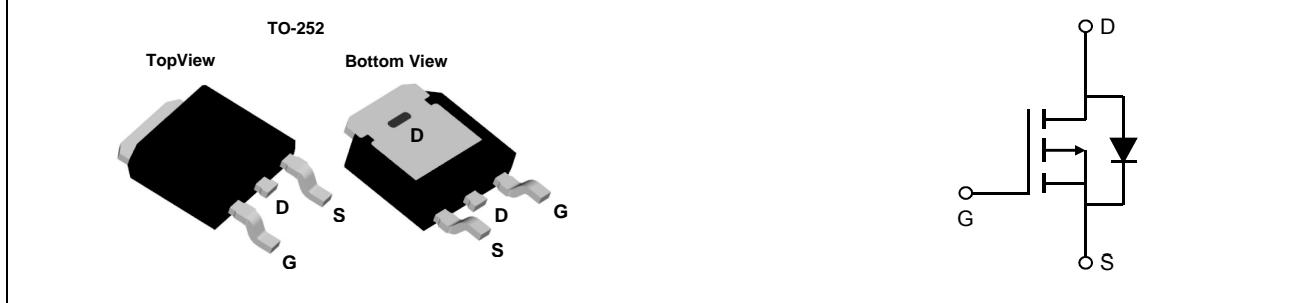


TMD15P06D

P-CHANNEL ENHANCEMENT MOSFET

General Description	Product Summary
<p>The TMD15P06D uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.</p> <ul style="list-style-type: none"> • Power switching application • Hard Switched and High Frequency Circuits • Uninterruptible Power Supply 	<p>VDS=-60V, ID=-16A $R_{DS(ON)} < 70m\Omega$ @ VGS=10V $R_{DS(ON)} < 90m\Omega$ @ VGS=4.5V</p> <p>100% UIS Tested 100% R_g Tested</p> 



Absolute Maximum Ratings@$T_j=25^\circ C$(unless otherwise specified)			
Symbol	Parameter	Rating	Units
VDS	Drain-Source Voltage	-60	V
VGS	Gate-Source Voltage	+20	V
I_D @ $T_c=25^\circ C$	Drain Current, V_{GS} @ 10V	-16	A
I_D @ $T_c=100^\circ C$	Drain Current, V_{GS} @ 10V	-10	A
IDM	Pulsed Drain Current ¹	-60	A
P_D @ $T_c=25^\circ C$	Total Power Dissipation	32.8	W
P_D @ $T_A=25^\circ C$	Total Power Dissipation	2	W
EAS	Single Pulse Avalanche Energy ⁴	32	mJ
TSTG	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C
R_{Thj-c}	Maximum Thermal Resistance, Junction-case	3.8	°C/W
R_{Thj-a}	Maximum Thermal Resistance, Junction-ambient (PCB mount) ³	62.5	°C/W

Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-60	-	-	V
RDS(ON)	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-10\text{A}$	-	-	70	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-7\text{A}$	-	-	90	$\text{m}\Omega$
VGS(th)	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-1	-	-3	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-10\text{V}, I_{\text{D}}=-10\text{A}$	-	21	-	S
IDSS	Drain-Source Leakage Current	$V_{\text{DS}}=-48\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-25	uA
IGSS	Gate-Source Leakage	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge	$I_{\text{D}}=-10\text{A}$ $V_{\text{DS}}=-30\text{V}$ $V_{\text{GS}}=-10\text{V}$	-	33	52.8	nC
Q_{gs}	Gate-Source Charge		-	6	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge		-	6	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=-30\text{V}$	-	11	-	ns
t_r	Rise Time	$I_{\text{D}}=-10\text{A}$ $R_G=3.3\Omega$ $V_{\text{GS}}=-10\text{V}$	-	21	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time		-	41	-	ns
t_f	Fall Time		-	42	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$ $V_{\text{DS}}=-30\text{V}$ $f=1.0\text{MHz}$	-	1860	2976	pF
C_{oss}	Output Capacitance		-	110	-	pF
C_{rss}	Reverse Transfer Capacitance		-	80	-	pF
V_{SD}	Forward On Voltage ²		-	-	-1.3	V
t_{rr}	Reverse Recovery Time	$I_{\text{S}}=-10\text{A}, V_{\text{GS}}=0\text{V}, \frac{dI}{dt}=-100\text{A}/\mu\text{s}$	-	21	-	ns
Q_{rr}	Reverse Recovery Charge		-	17	-	nC

Notes:

1.Pulse width limited by Max. junction temperature.

2.Pulse test

3.Surface mounted on 1 in² copper pad of FR4 board

4.Starting $T_j=25^\circ\text{C}$

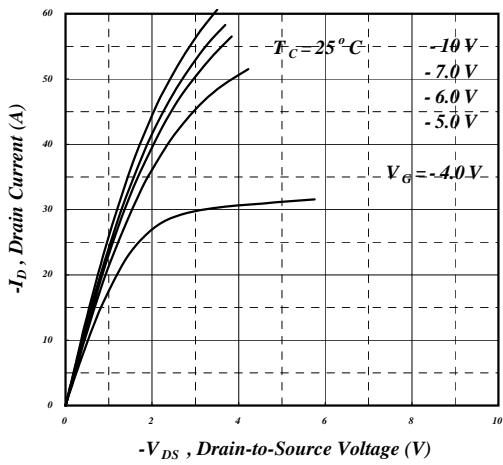


Fig 1. Typical Output Characteristics

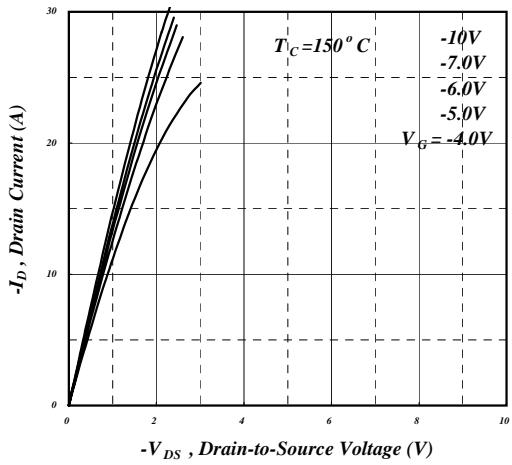


Fig 2. Typical Output Characteristics

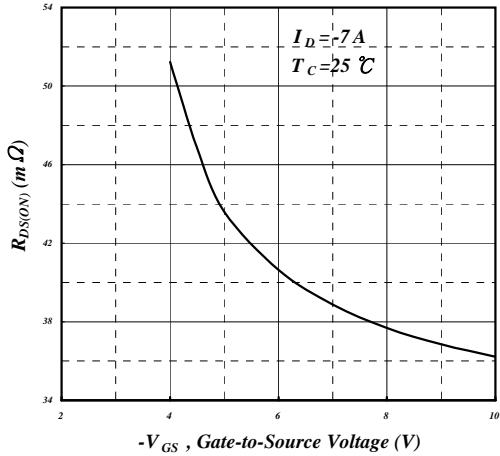


Fig 3. On-Resistance v.s. Gate Voltage

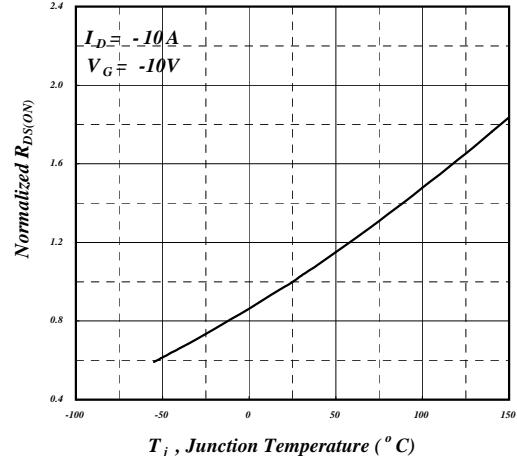


Fig 4. Normalized On-Resistance v.s. Junction Temperature

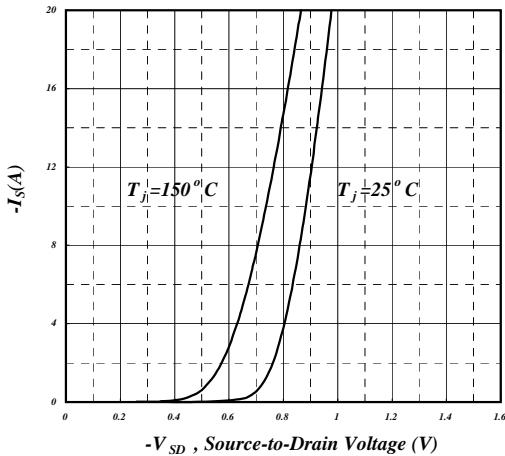


Fig 5. Forward Characteristic of Reverse Diode

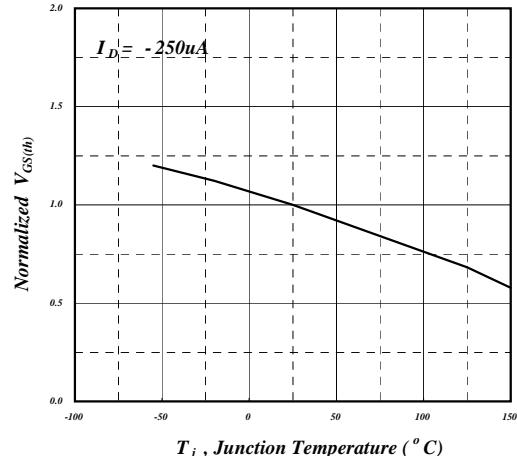


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

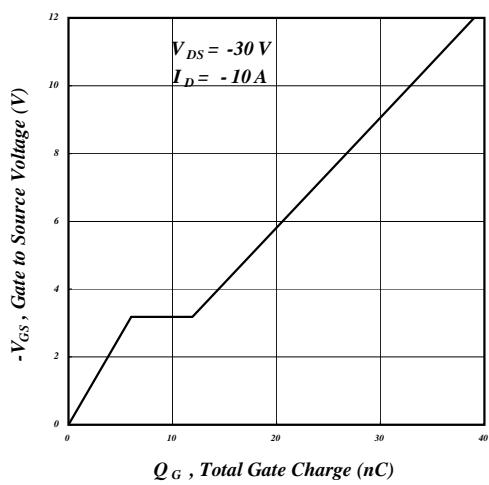


Fig 7. Gate Charge Characteristics

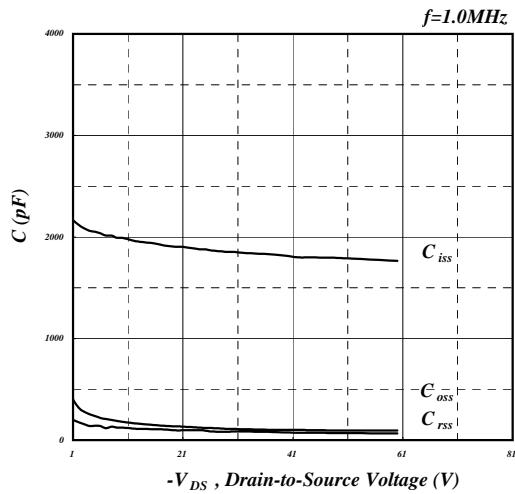


Fig 8. Typical Capacitance Characteristics

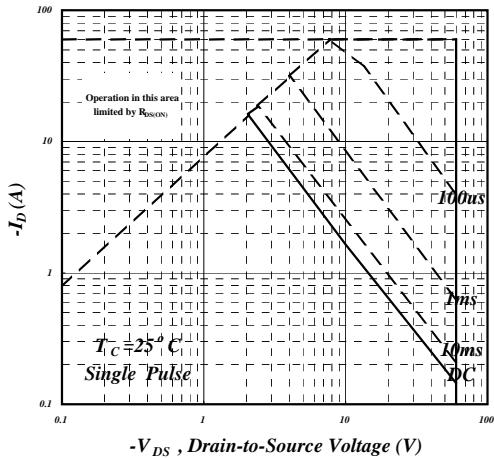


Fig 9. Maximum Safe Operating Area

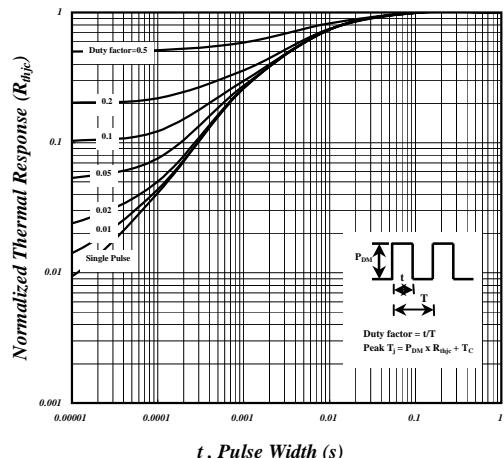


Fig 10. Effective Transient Thermal Impedance

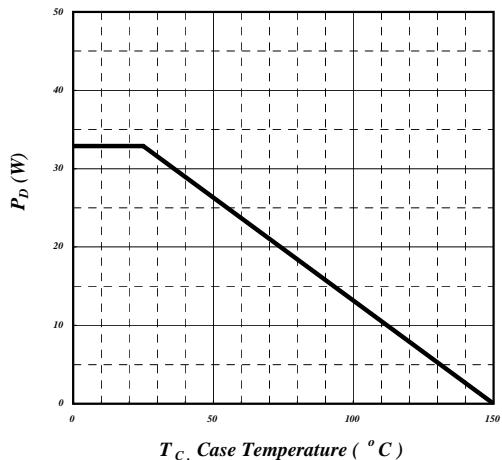


Fig 11. Typical Power Dissipation

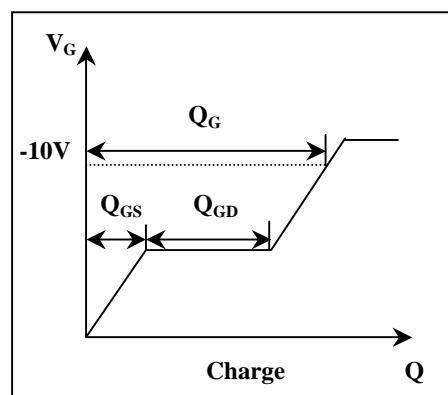


Fig 12. Gate Charge Waveform

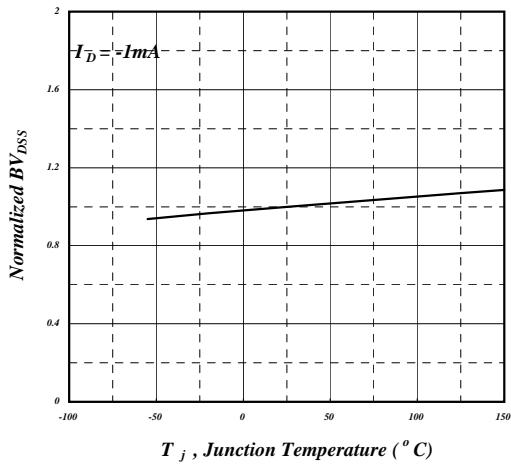


Fig 13. Normalized BV_{DSS} v.s. Junction Temperature

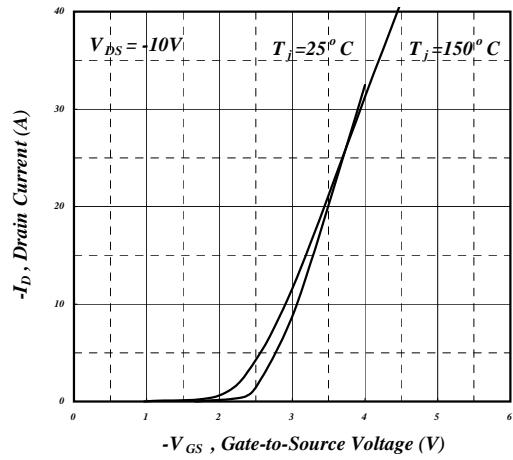


Fig 14. Transfer Characteristics

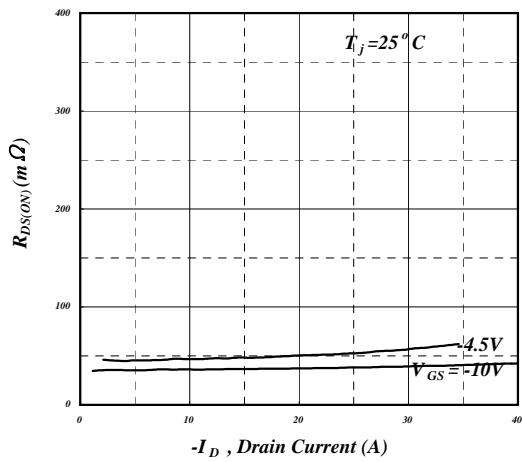


Fig 15. Typ. Drain-Source on State Resistance

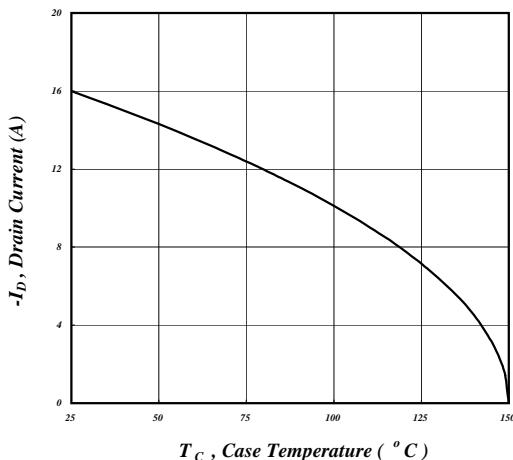
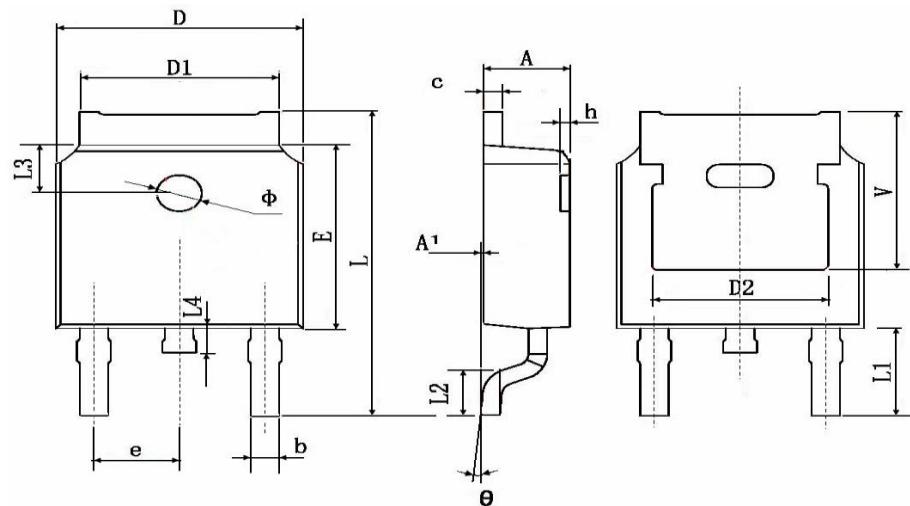


Fig 16. Drain Current v.s. Case Temperature

TO-252 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.660	0.860	0.026	0.034
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 TYP.		0.190 TYP.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.800	10.400	0.386	0.409
L1	2.900 TYP.		0.114 TYP.	
L2	1.400	1.700	0.055	0.067
L3	1.600 TYP.		0.063 TYP.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.350 TYP.		0.211 TYP.	